



Click [here](#) for the 3D model.

General Information

Series	Array Comm COG Flex
Style	SMD Array
Description	SMD, MLCC, Array, Flex Termination, Class II
RoHS	Yes
Termination	Flexible Termination
AEC-Q200	No
Chip Size	0612
MSL	1

Dimensions

L	1.6mm +/-0.2mm
W	3.2mm +/-0.2mm
T	0.8mm +/-0.10mm
P	0.8mm +/-0.10mm

Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

Specifications

Capacitance	330 pF
Tolerance	20%
Voltage DC	25 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Insulation Resistance	100 GOhms